

30V Dual P-Channel Power MOSFET

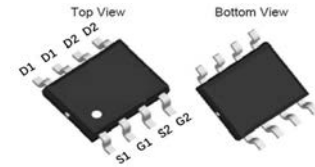
DESCRIPTION :

- Excellent $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% ΔV_{DS} Tested
- Pb-Free Lead Plating
- RoHS compliant

V_{DSS}	-30V
$I_D (T_A=25^\circ C)$	-5.1A
$R_{DS(ON)_Typ. @V_{GS}=-10V}$	33m Ω

TYPICAL APPLICATIONS :

- Load Switch
- PWM Application
- Power Management



SOP-8

MAXIMUM RATINGS (at $T_A = 25^\circ C$, unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_A=25^\circ C$ $T_A=100^\circ C$	I_D	-5.1 -3.2	A
Pulsed Drain Current ⁽¹⁾		I_{DM}	-20	A
Single Pulsed Avalanche Energy ⁽²⁾		E_{AS}	12	mJ
Power dissipation		P_D	1.5	W
Junction & Storage temperature Range		T_J, T_{STG}	-55~+150	$^\circ C$

- Notes :
1. Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting $T_J=25^\circ C$, $V_{DD} = -15V$, $V_{GS} = -10V$, $R_G=25\Omega$, $L=0.5mH$, $I_{AS} = -7A$, $V_{DD}=0V$ during time in avalanche.

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient	$R_{\theta JA}$	83	$^\circ C/W$

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage $V_{GS} = 0\text{V}$, $I_D = -250\mu\text{A}$	$V_{(BR)DSS}$	-30			V
Zero Gate Voltage Drain Current $V_{DS} = -30\text{V}$, $V_{GS} = 0\text{V}$	I_{DSS}			-1	μA
Gate-Source Leakage Current $V_{GS} = \pm 20\text{V}$, $V_{DS} = 0\text{V}$	I_{GSS}			± 100	nA
Gate-Source threshold voltage $V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$	$V_{GS(th)}$	-1.0	-1.8	-2.5	V
Drain-Source On-State Resistance $V_{GS} = -10\text{V}$, $I_D = -5\text{A}$ $V_{GS} = -4.5\text{V}$, $I_D = -4\text{A}$	$R_{DS(on)}$		33 49	43 64	m Ω
Input capacitance $f = 1\text{MHz}$, $V_{DS} = -15\text{V}$, $V_{GS} = 0\text{V}$	C_{iss}		540		pF
Output capacitance $f = 1\text{MHz}$, $V_{DS} = -15\text{V}$, $V_{GS} = 0\text{V}$	C_{oss}		75		pF
Reverse transfer capacitance $f = 1\text{MHz}$, $V_{DS} = -15\text{V}$, $V_{GS} = 0\text{V}$	C_{rss}		57		pF
Total Gate Charge $V_{DS} = -15\text{V}$, $I_D = -2\text{A}$, $V_{GS} = -10\text{V}$	Q_G		11		nC
Gate to Source Charge $V_{DS} = -15\text{V}$, $I_D = -2\text{A}$, $V_{GS} = -10\text{V}$	Q_{GS}		2		nC
Gate to Drain Charge $V_{DS} = -15\text{V}$, $I_D = -2\text{A}$, $V_{GS} = -10\text{V}$	Q_{GD}		2		nC
Turn-on delay time $V_{DD} = -15\text{V}$, $V_{GS} = -10\text{V}$, $I_D = -2\text{A}$, $R_{GEN} = 3\Omega$	$t_{d(ON)}$		3		ns
Rise time $V_{DD} = -15\text{V}$, $V_{GS} = -10\text{V}$, $I_D = -2\text{A}$, $R_{GEN} = 3\Omega$	t_r		2		ns
Turn-off delay time $V_{DD} = -15\text{V}$, $V_{GS} = -10\text{V}$, $I_D = -2\text{A}$, $R_{GEN} = 3\Omega$	$t_{d(OFF)}$		26		ns
Fall time $V_{DD} = -15\text{V}$, $V_{GS} = -10\text{V}$, $I_D = -2\text{A}$, $R_{GEN} = 3\Omega$	t_f		15		ns

Body Diode

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = -5.1A$	V_{SD}			-1.2	V
Maximum Continuous Body Diode Forward Current	I_S			-5.1	A
Maximum Pulsed Body Diode Forward Current	I_{SM}			-20	A
Revers Recovery Time $I_F = -2A, di/dt = 100A/\mu s$	T_{rr}		9		ns
Revers Recovery Charge $I_F = -2A, di/dt = 100A/\mu s$	Q_{rr}		3		nC

Typical Performance Characteristics

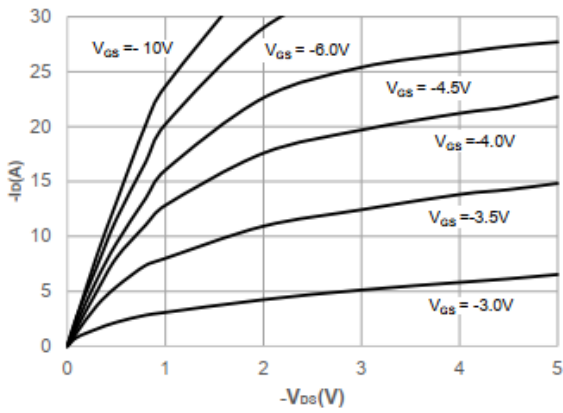


Figure 1. Output Characteristics

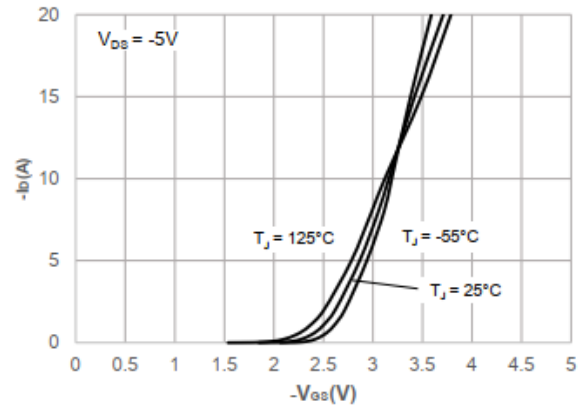


Figure 2. Typical Transfer Characteristics

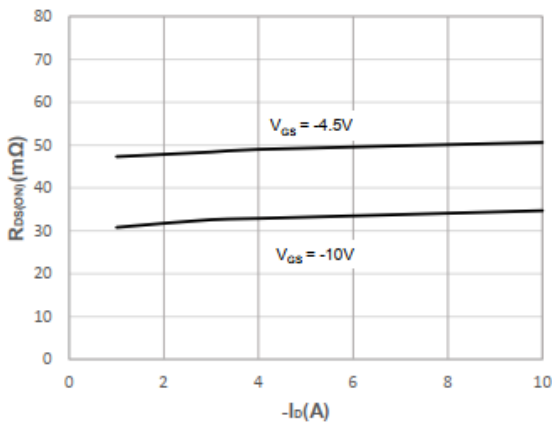


Figure 3. On-resistance vs. Drain Current

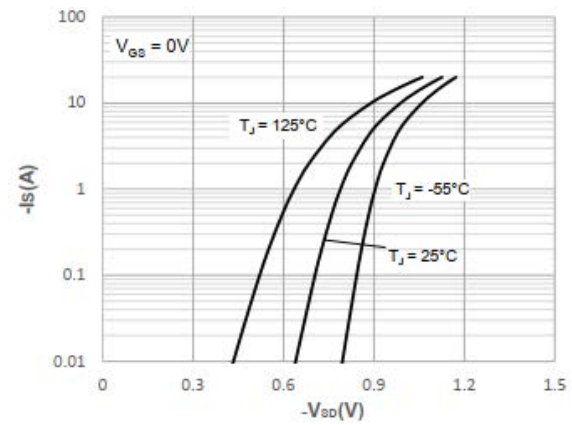


Figure 4. Body Diode Characteristics

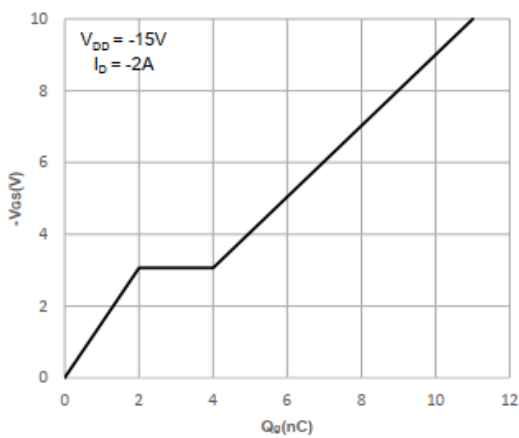


Figure 5. Gate Charge Characteristics

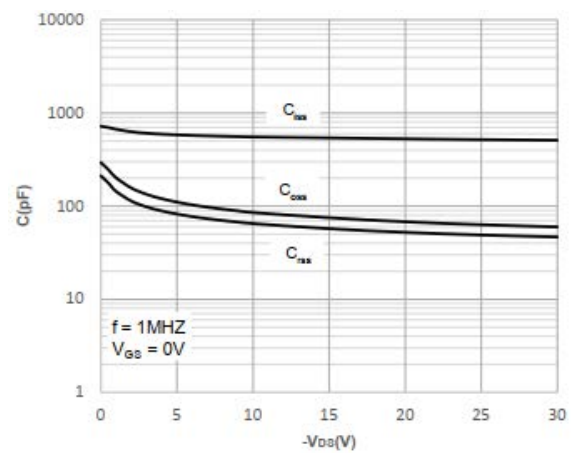


Figure 6. Capacitance Characteristics

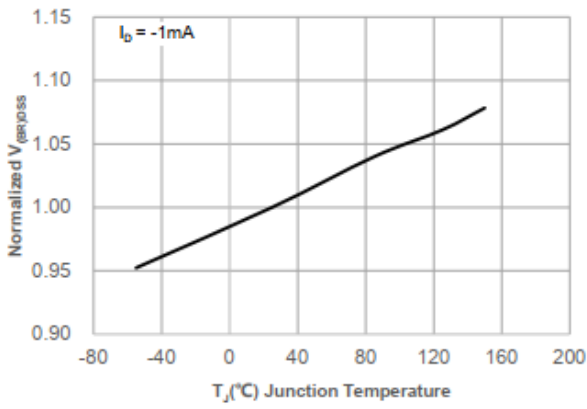


Figure 7. Normalized Breakdown voltage vs. Junction Temperature

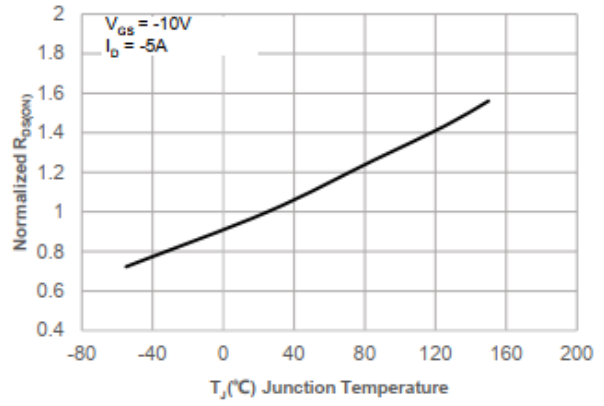


Figure 8. Normalized on Resistance vs. Junction Temperature

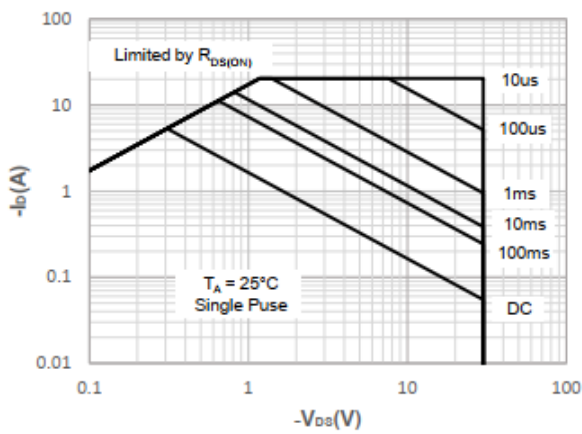


Figure 9. Maximum Safe Operating Area

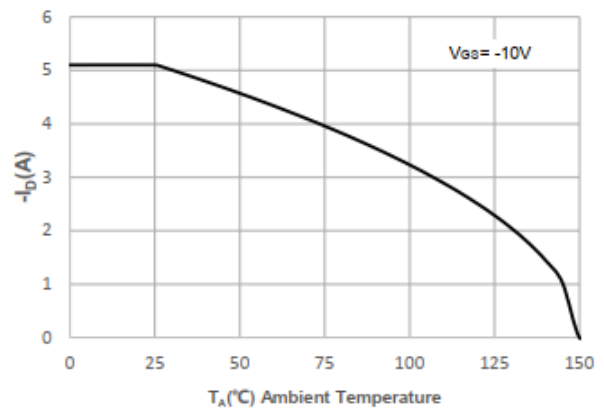


Figure 10. Maximum Continuous Drain Current vs. Ambient Temperature

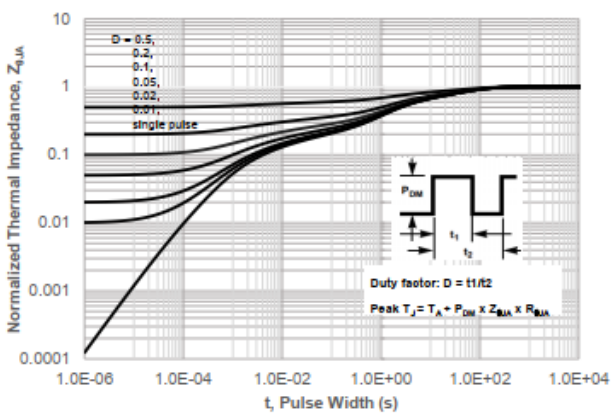


Figure 11. Normalized Maximum Transient Thermal Impedance

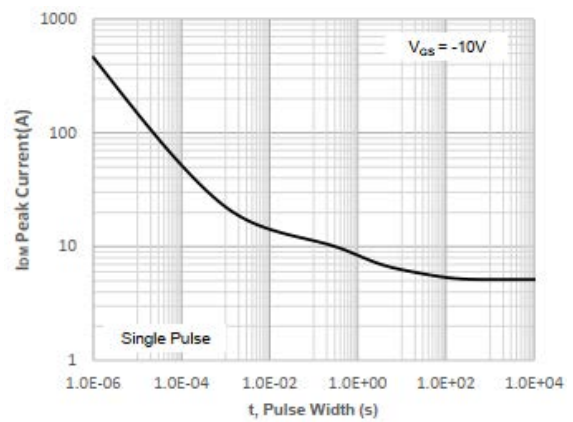
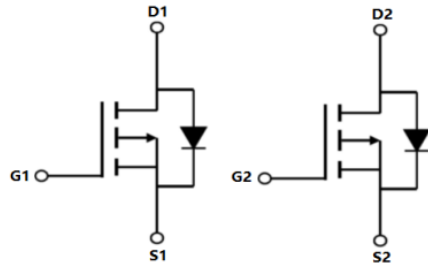
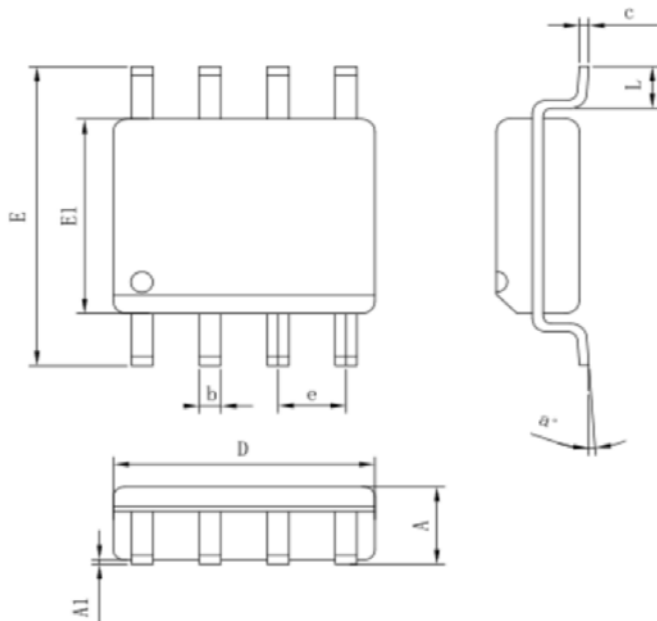


Figure 12. Peak Current Capacity

• Circuit diagram :



• Package outlines : Dimensions in (mm)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.75
A1	0.10	--	0.23
b	0.35	--	0.48
c	0.19	--	0.25
D	4.70	4.90	5.00
E	5.80	6.00	6.20
E1	3.70	3.90	4.10
e	1.27BSC		
L	0.50	--	0.80
a*	0*	--	8*

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